

Form PTO-1595 (Rev. 08/05)
OMB No. 0651-0027 (exp. 6/30/2008)

U.S. DEPARTMENT OF COMMERCE
United States Patent and Trademark Office

RECORDATION FORM COVER SHEET
PATENTS ONLY

6737-99

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

Interconnect Devices, Inc.

2. Name and address of receiving party(ies)

Name: Madison Capital Funding, LLC,

Internal Address: _____ as agent

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) April 3, 2009

- Assignment
- Security Agreement
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other First Amendment to Patent Security Agreement

Street Address: 30 S. Wacker

City: Chicago

State: IL

Country: USA Zip: 60606

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Laura Konrath

Internal Address: Winston & Strawn LLP

Street Address: 35 W. Wacker Dr.

City: Chicago

State: IL Zip: 60601

Phone Number: 312-558-6352

Fax Number: 312-558-5700

Email Address: lkonrath@winston.com

6. Total number of applications and patents involved: 37

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 1,480

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

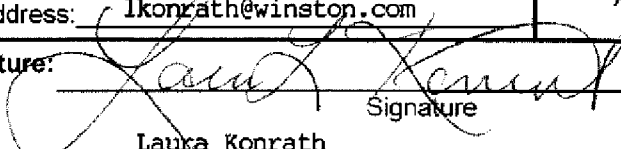
8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number 232428

Authorized User Name Laura Konrath

9. Signature:



Signature

4/20/09
Date

Laura Konrath

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

CH \$1320.00 232428 60587761

Continuation Item 4

EXHIBIT A

PATENT REGISTRATIONS AND PATENT APPLICATIONS

Title Short Title	Country App. No. Grant No.	Status App. Date Grant Date
..... APPARATUS FOR TESTING A NONPACKAGED DIE	United States 08/060,614 5,656,945	Granted 5/12/1993 8/12/1997
..... SHEET METAL INTERCONNECT ARRAY	United States 29/194,881 D525,207	Granted 12/2/2003 7/18/2006
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..... MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	United States 11/125,035 7,217,138	Granted 5/9/2005 5/15/2007
..... MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	WO PCT/US2004/028200	Gone National 8/31/2004
..... MULTIPATH INTERCONNECT WITH MEANDERING CONTACT CANTILEVERS	Korea 2006-7010770	Pending 8/31/2004
..... SEE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID PROVIDING SPRING SUSPENSION	United States 10/759,338 7,059,865	Granted 1/16/2004 6/13/2006
..... SEE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID PROVIDING SPRING SUSPENSION	Malaysia PI20043349	Pending 8/18/2004

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BUTTON CONTACT FOR SURFACE MOUNTING AN IC DEVICE TO A CIRCUIT BOARD	United States 08/531,367 5,629,837	Granted 9/20/1995 5/13/1997
MODULAR SEMICONDUCTOR PACKAGE TESTING CONTACTOR SYSTEM	Taiwan 94123694	Pending 7/13/2005
MODULAR CONTACTOR SYSTEM, SPRING PROBE BASED	United States 60/587,761	Completed 7/14/2004

MODULAR SEMICONDUCTOR PACKAGE TESTING CONTACTOR SYSTEM	United States 11/177,673 7,189,092	Granted 7/8/2005 3/13/2007
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ACTIVE TEST SOCKET	United States 11/671,963	Pending 2/6/2007
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ACTIVE TEST SOCKET	United States 60/765,555	Completed 2/6/2006
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INTERCONNECT ASSEMBLY FOR A PROBE CARD	United States 11/198,995 7,217,139	Granted 8/8/2005 5/15/2007
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INTERCONNECT ASSEMBLY FOR A PROBE CARD	WO PCT/AUS2005/028240	Gone National 8/9/2005
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COMPRESSIVE CONDUCTORS FOR SEMICONDUCTOR TESTING	United States 11/671,942	Pending 2/6/2007
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COMPRESSIVE CONDUCTORS FOR SEMICONDUCTOR TESTING	United States 60/765,710	Completed 2/6/2006
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CRIMPED TUBE ELECTRICAL TEST SOCKET PIN	United States 11/671,986 7,297,004	Granted 2/6/2007 11/20/2007
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CRIMPED TUBE ELECTRICAL TEST SOCKET PIN	United States 60/765,549	Completed 2/6/2006
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MICRO- COAX/COMPRESSIBLE CONDUCTOR CONTACTOR	United States 11/675,521	Pending 2/15/2007
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MICRO- COAX/COMPRESSIBLE CONDUCTOR CONTACTOR	United States 60/775,301	Completed 2/21/2006
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INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 60/735,937	Completed 11/10/2005
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INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 60/735,939	Completed 11/10/2005
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BUNDLE PROBE ^{United States} APPARATUS FOR MULTIPLE TERMINAL CONTACT	Granted 09/775,676 7,064,564	2/1/2001 6/20/2006
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SEE-SAW INTERCONNECT ASSEMBLY WITH DIELECTRIC CARRIER GRID	China 200480042418.3	Pending 8/30/2004
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PROVIDING SPRING
SUSPENSION

INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 11/558,591	Pending 11/10/2006
INTERCONNECT ASSEMBLY FOR TESTING INTEGRATED CIRCUIT PACKAGES	United States 11/558,603 7,402,051	Granted 11/10/2006 7/22/2008
INTERCONNECT ASSEMBLY FOR A PROBE CARD	China 200580026854.6	Pending 8/9/2005
INTERCONNECT ASSEMBLY FOR A PROBE CARD	Korea 2007-7004850	Pending 8/9/2005
INTERCONNECT ASSEMBLY FOR A PROBE CARD	Philippines 2007-500354	Pending 8/9/2005
TEST INTERCONNECT	United States 12/054,281	Pending 3/24/2008
IMPEDANCE-MATCHED TEST SOCKET AND METHOD OF MANUFACTURING SAME	United States 61/022,675	Pending 1/22/2008
IMPEDANCE-MATCHED TEST SOCKET OF MANUFACTURING SAME	United States 61/038/614	Pending 3/21/2008
SPRING PROBE	United States 12/105,922	Pending 4/18/2008

PATENT LICENSES

- Irrevocable and perpetual, non-exclusive, royalty-free, fully-paid up, and worldwide license to make, use, sell, import, export, copy, prepare derivative works based on, distribute in any manner or medium, and otherwise commercially exploit the following intellectual property in connection with the package test division which engages in the design, manufacturing, marketing and sale of machined spring probe based test sockets and related components which are used by semiconductor companies in validation testing of integrated circuits (the "Business"):

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Execution Copy

FIRST AMENDMENT TO PATENT SECURITY AGREEMENT

This FIRST AMENDMENT TO PATENT SECURITY AGREEMENT (this "Amendment"), dated as of April 3, 2009, is between INTERCONNECT DEVICES, INC., a Delaware corporation (the "Grantor") and MADISON CAPITAL FUNDING LLC, as "Agent" for the Lenders.

WITNESSETH:

WHEREAS, the Grantor and the Agent are party to that certain Patent Security Agreement dated as of May 11, 2007 (as amended, restated, supplemented or otherwise modified from time to time, the "Patent Security Agreement");

WHEREAS, since the filing of the Patent Security Agreement, the Grantor has acquired additional Patents;

WHEREAS, the Grantor wishes to amend the Patent Security Agreement as set forth herein, and the Agent is agreeable to the same, subject to the terms and conditions hereof;

NOW, THEREFORE, in consideration of the premises and of the mutual covenants contained herein, and other good and valuable consideration the receipt and adequacy of which are hereby acknowledged, the parties hereto hereby agree as follows:

1. Amendment. Schedule 1 of the Patent Security Agreement is amended by adding thereto the Patent Applications, the Patent Registrations and the Patent Licenses listed on Exhibit A attached hereto.

2. Miscellaneous. The parties hereto hereby further agree as follows:

(a) Counterparts. This Amendment may be executed in one or more counterparts, each of which, when executed and delivered, shall be deemed to be an original and all of which counterparts, taken together, shall constitute but one and the same document with the same force and effect as if the signatures of all of the parties were on a single counterpart, and it shall not be necessary in making proof of this Amendment to produce more than one (1) such counterpart.


(b) Governing Law. THIS AMENDMENT SHALL BE GOVERNED BY, AND CONSTRUED AND ENFORCED IN ACCORDANCE WITH, THE INTERNAL LAWS AND DECISIONS OF THE STATE OF ILLINOIS (WITHOUT REFERENCE TO CONFLICT OF LAWS PRINCIPLES).

(c) No Other Amendments. Except as expressly amended hereby, the Patent Security Agreement shall remain unaltered and in full force and effect.

[signature page follows]

IN WITNESS WHEREOF, the undersigned have executed this Amendment as of the day and year first above written.

INTERCONNECT DEVICES, INC.

By: 
Name: Mark W. Deuel
Title: Chief Financial Officer, Treasurer and
Secretary

**MADISON CAPITAL FUNDING LLC,
as Agent**

By: _____
Name: _____
Title: _____

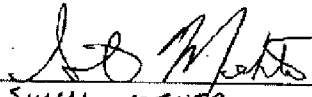
Signature Page to First Amendment to Patent Security Agreement

IN WITNESS WHEREOF, the undersigned have executed this Amendment as of the day and year first above written.

INTERCONNECT DEVICES, INC.

By: _____
Name: _____
Title: _____

**MADISON CAPITAL FUNDING LLC,
as Agent**

By:  _____
Name: SUNIL MEHTA
Title: VICE PRESIDENT

Signature Page to First Amendment to Patent Security Agreement

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- a. US Patent Application – “Thermally Balanced Heatsinks” (Docket No. 9606-283)
(inventors – Chris Lopez and Trevor Moody)

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